



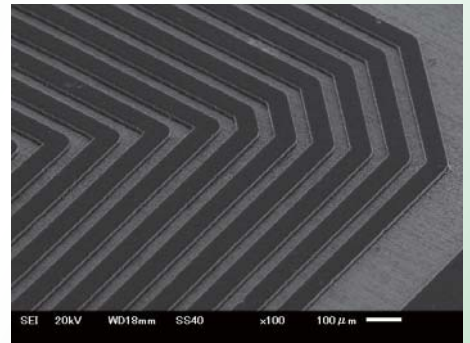
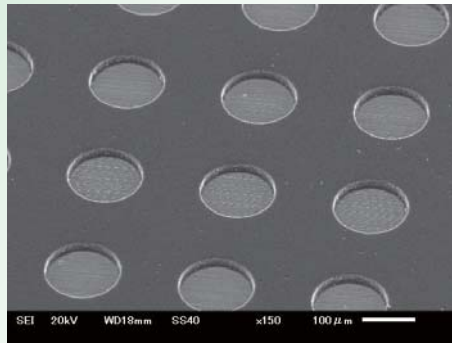
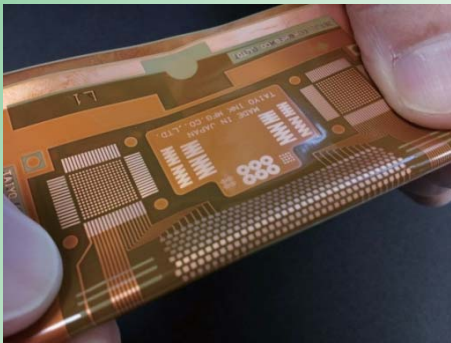
感光性カバーレイフィルム

Photo Imageable Cover Lay Film



特徴 Features

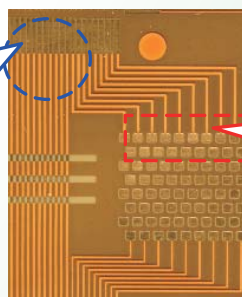
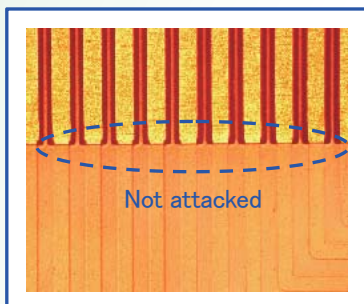
- 高解像性と高屈曲性の両立を実現した感光性ポリイミドフィルム
Photo imageable polyimide film with coexistence of high resolution and high bendability
- 現行のプリント配線板製造ラインへの適用を実現
Applicable to current PWB photolithography process
- 優れた耐熱性と絶縁信頼性と難燃性(VTM-0相当)を実現
Excellent heat resistance, insulation reliability and flame resistance (VTM-0 equivalent)



特性 Properties

Item	Condition	Result
Pencil hardness	JIS 5600	4H
Acid resistance	10vol% H ₂ SO ₄ aq. 25deg.C × 20 min	Pass
Alkaline resistance	10wt% NaOHaq. 25deg.C × 20 min	Pass
Heat resistance	Solder floating 288deg.C × 10 sec	Pass
Au plating resistance	ENIG Ni : 4um Au : 0.1um	Pass
Tg	TMA	160deg.C
Bendability	180deg. folding	above 20 times

★ENIG resistance [Ni : 4.0um Au : 0.1um]



★Solder heat resistance [288deg.C × 10sec × 2 times]

